

USE OF GOLD SURFACE FINISH
ON A COPPER WIRE-BOND SUBSTRATE,
METHOD OF MAKING SAME, AND
METHOD OF TESTING SAME

ABSTRACT OF THE DISCLOSURE

A wire-bonding substrate is described. The wire-bonding substrate includes a copper metallization and a gold surface finish disposed above and on the copper metallization. The gold surface finish completes a structure that includes at least one of a bond finger for wire bonding of a first side of the substrate, and a land pad for a ball attach on a second side of the substrate. A process of forming the surface finish is also disclosed. An electronic package is also disclosed that uses the surface finish on the wire-bonding substrate. A method of assembling an electronic package is also disclosed that includes the surface finish on the wire-bonding substrate. A computing system is also described that includes the surface finish on the wire-bonding substrate.

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